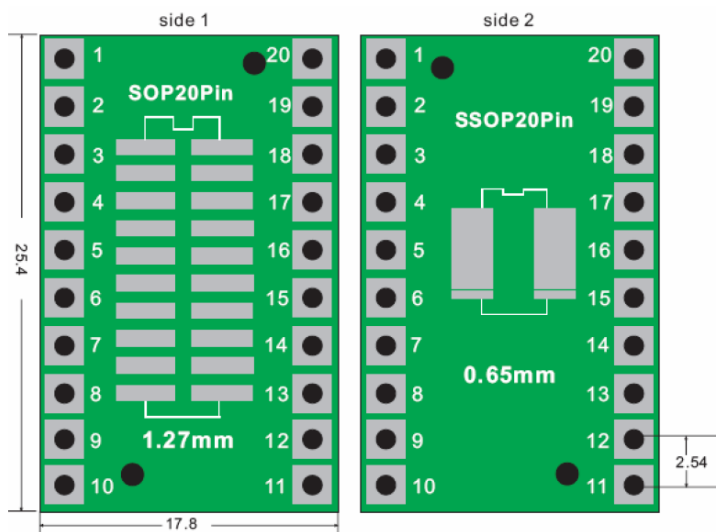


No. 1571114



Technical data

Function:
SOP20 & SSOP20 package to DIP

Technical Data:

Board Material	FR-4
SMD package	SOP20 (side 1)
	SSOP20 (side 2)
Pitch	1.27 (Side 1)
	0.65 (Side 2)
Board Thickness	1.6mm ± 0.1mm
Surface Technioque	Spray tin 5-8um
Copper Thickness	35um ± 5um
Solderability	260°C at 3s - 1.1%
Flammability	V-0
Surface Resistivity	1.0 x 10 ⁶ MΩ
Volume Resistivity	1.0 x 10 ⁸ MΩ - cm
Arc Resistance	125sec.